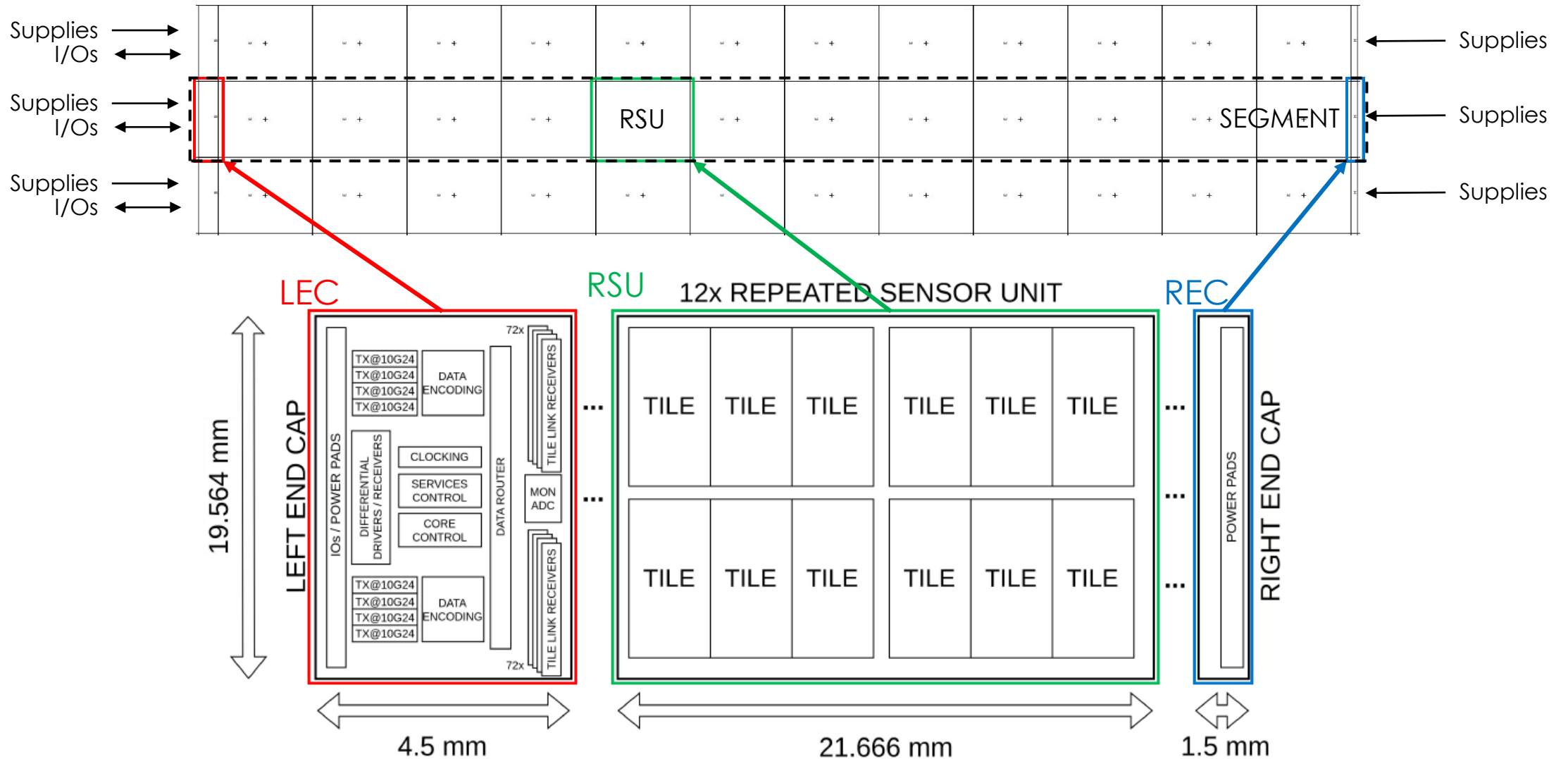


SVT Readout

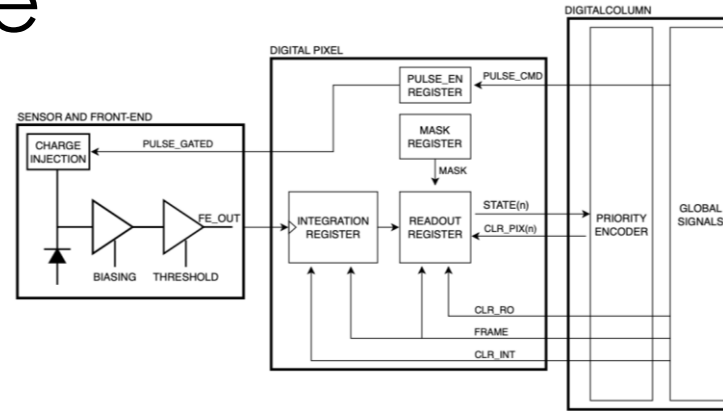
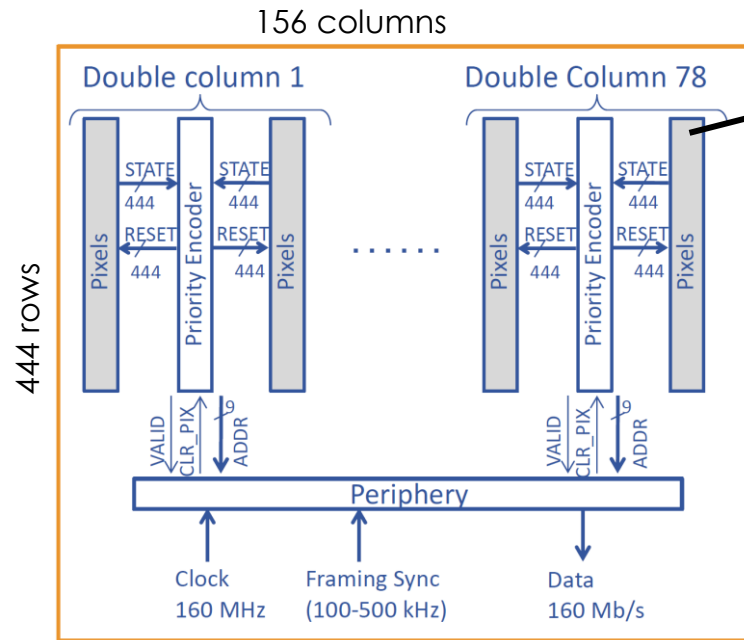
J. Schambach

ORNL is managed by UT-Battelle LLC for the US Department of Energy

MOSAIX Architecture



Domain (Tile) Architecture



444 x 156 pixels / domain
 831 168 pixels per RSU
 144 domains / segment
 9.974 Mpixels / segment

In pixel:

- Amplification
- Discrimination
- Hit integration register and readout register
- Test charge injection
- Digital pulsing
- Masking

Digital pixel designed with low-leakage, high reliability std cells

20.8 μm x 22.8 μm pixel pitch(*)
 Continuously active front-end (40 nW typ.)
 Global shutter
 Zero-suppressed matrix readout
 Continuous readout mode
 Integration time: 2 μs to 2¹⁶*25ns = 1.6384ms

(*) **Baseline: 20.8 μm * 22.8 μm**
 Abs. Max: 22.5 μm * 25 μm

On-chip Readout Scheme in the Periphery

Framing time base re-generated in each TILE periphery

FRAME local signal synchronizes pixels, Region Readout and Top Readout

Global SYNC input signal *aligns in time* the integration intervals across tiles

Four parallel readout processes in each tile

Regions have 38 or 40 columns

Double columns in one region are sequentially read out

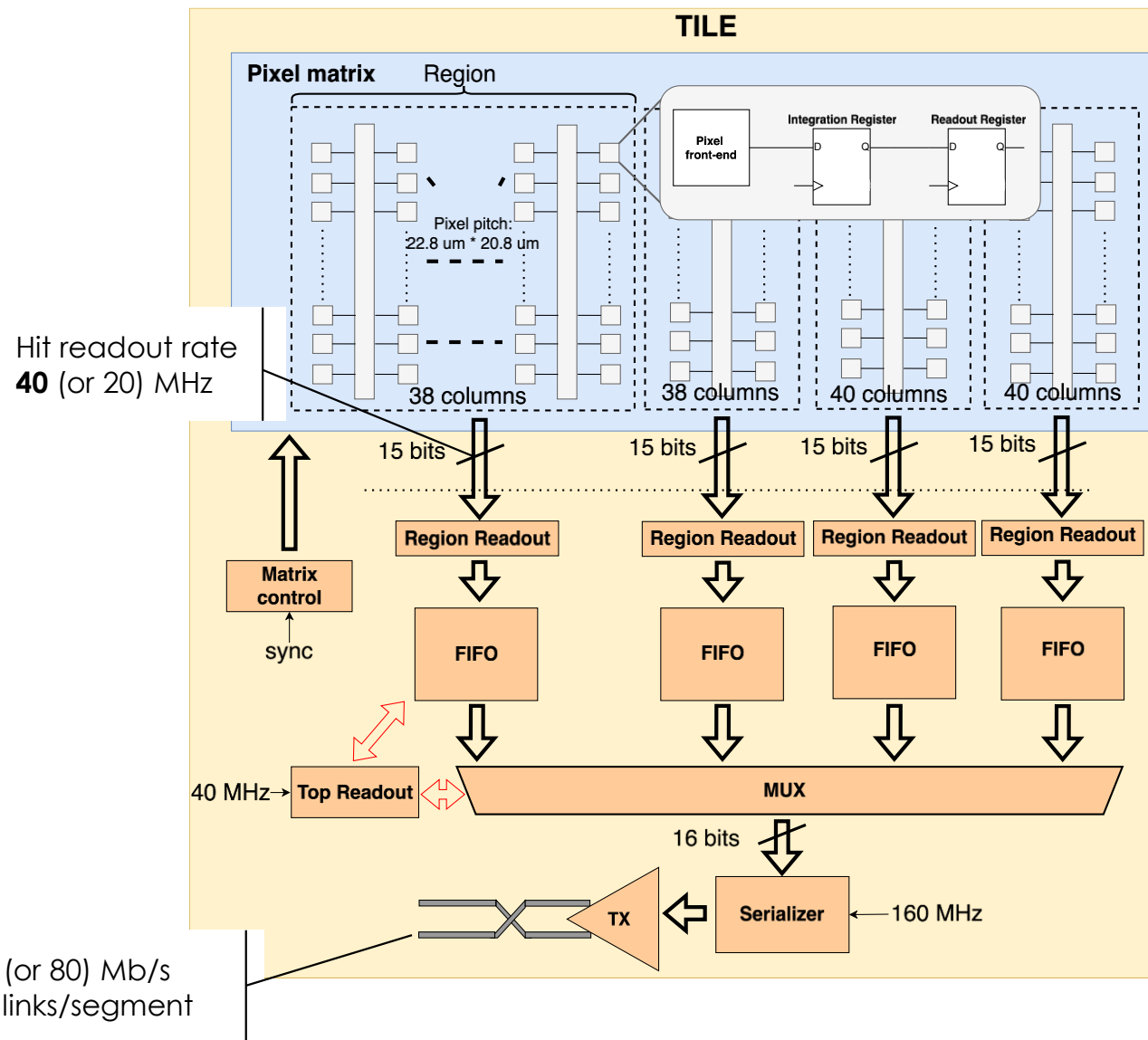
Region data packet is stored in FIFOs

Double columns and full regions can be masked

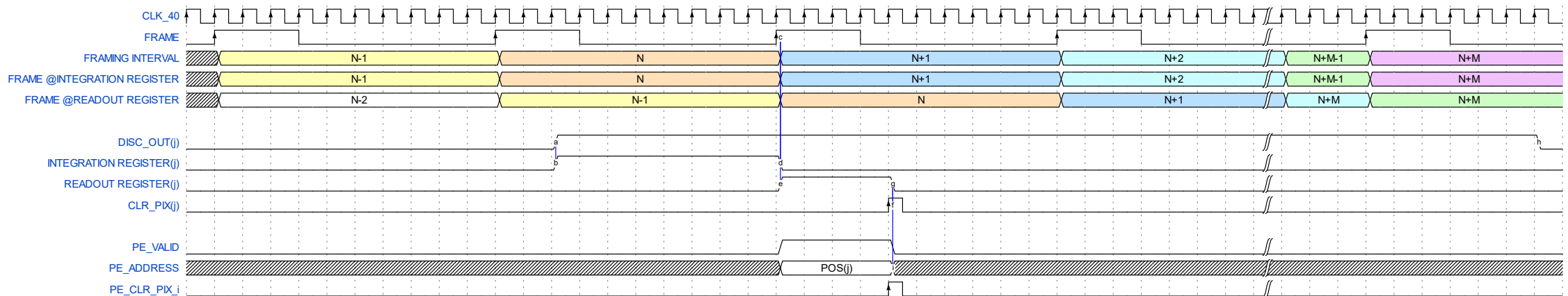
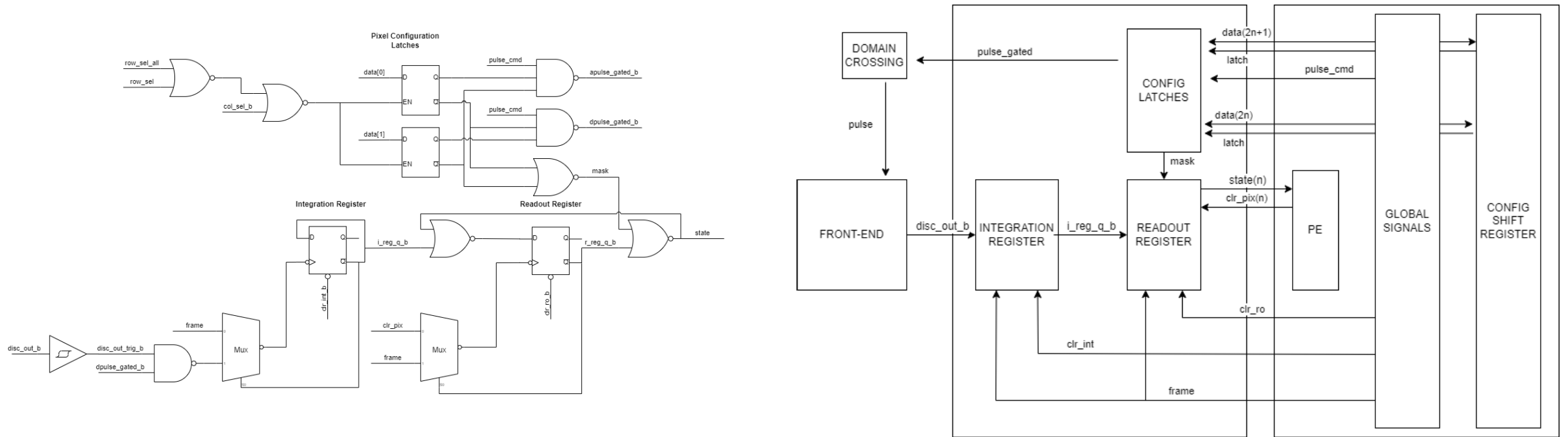
Serial transmission of tile packet to LEC

Top readout aggregates region data packets for the same frame interval

Tile transmits one data packet for each frame interval, in order

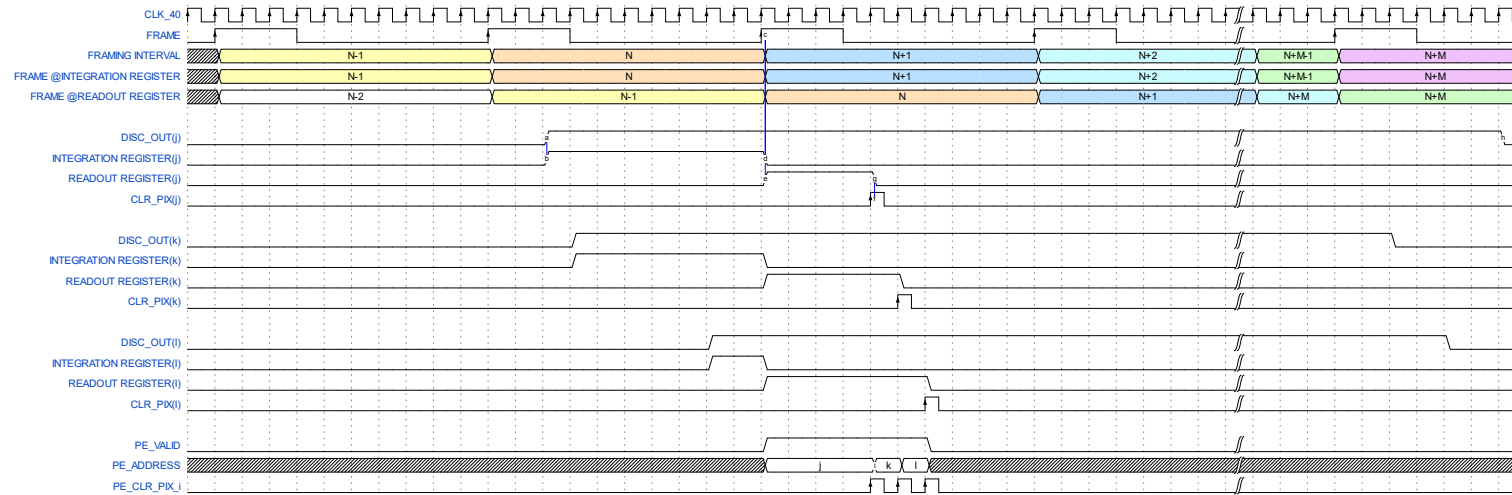


Tile Data Output

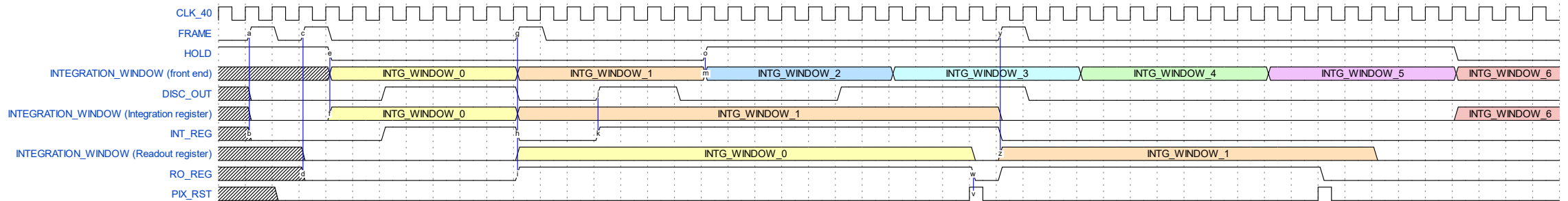


Pixel Array Readout Waveforms

Hits from one collision can be recorded in consecutive frame packets (time walk and spread of FRAME signals)

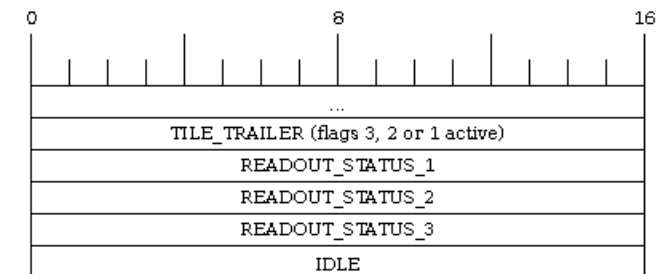
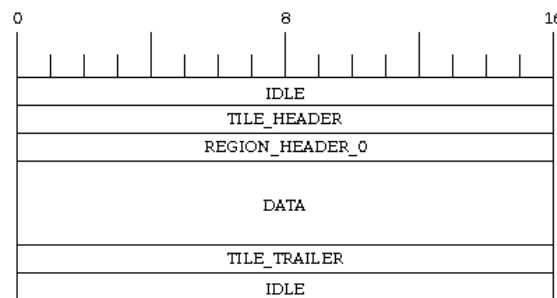
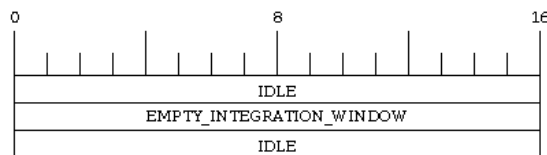
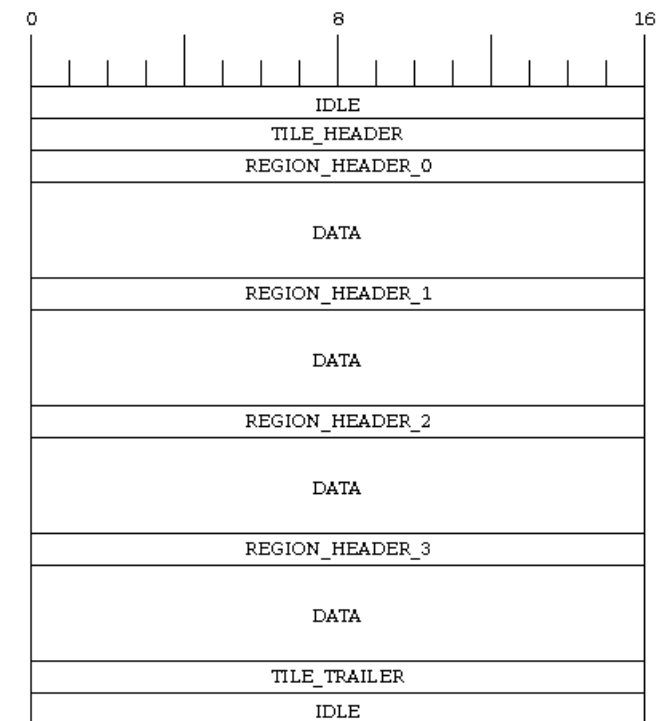


Region frame readout time can exceed the framing interval (from drop mode with priority to earliest frames)

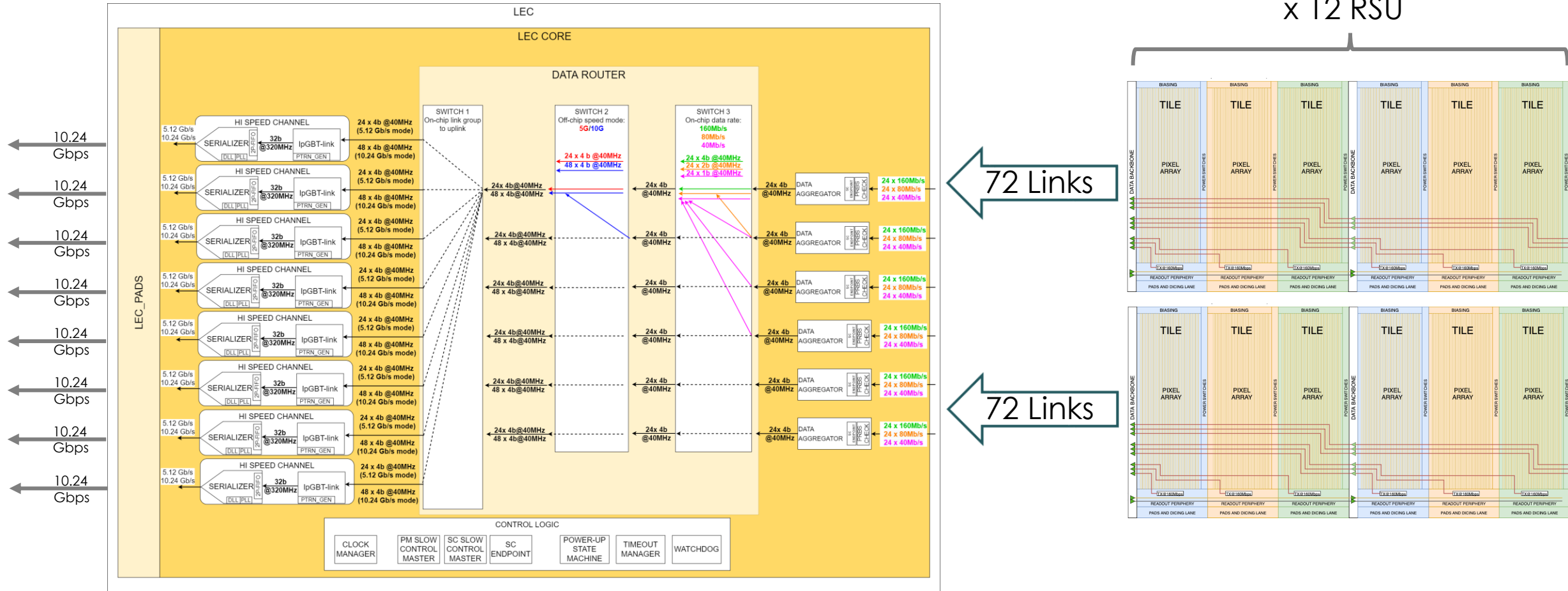


Tile Data Protocol

READOUT PROTOCOL																
Word type	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
TILE_HEADER	1	1	0	0	0	Reserved[1:0]			Tile_Address[8:0]						Top/Bottom	
REGION_HEADER	1	0	0	RRUAddress[1:0]		Integration_Window_Counter[10:0]										
DATA	0	Pixel_Address_X[8:0]								Pixel_Address_Y[5:0]						
DATA_EXTENSION	1	0	1	0	0	Pixel_Hit_Map[8:0]										
EMPTY_INTEGRATION_WINDOW	1	0	1	0	1	Integration_Window_Counter[10:0]										
TILE_TRAILER	1	0	1	1	Tile_Trailer_Flags[3:0]				Checksum[7:0]							
READOUT_STATUS_1	1	1	0	1	Readout_Status_Flags[3:0]			Integration_Window_Counter[31:24]								
READOUT_STATUS_2	1	1	1	0	Integration_Window_Counter[23:12]											
READOUT_STATUS_3	1	1	1	1	Integration_Window_Counter[11:0]											
IDLE	1	1	0	0	1	0	1	0	1	0	1	0	1	0	1	0



Data Flow – From Tiles to Left Endcap



12-RSU MOSAIX (SVT IB)

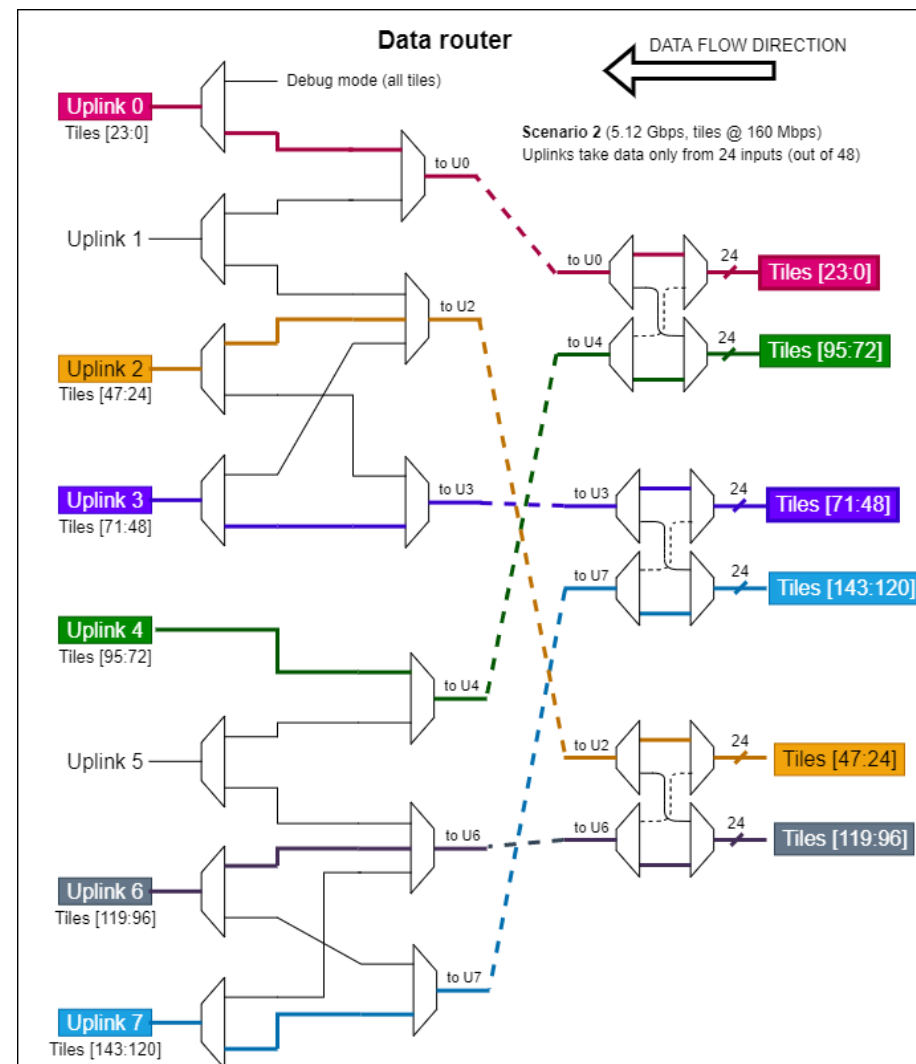
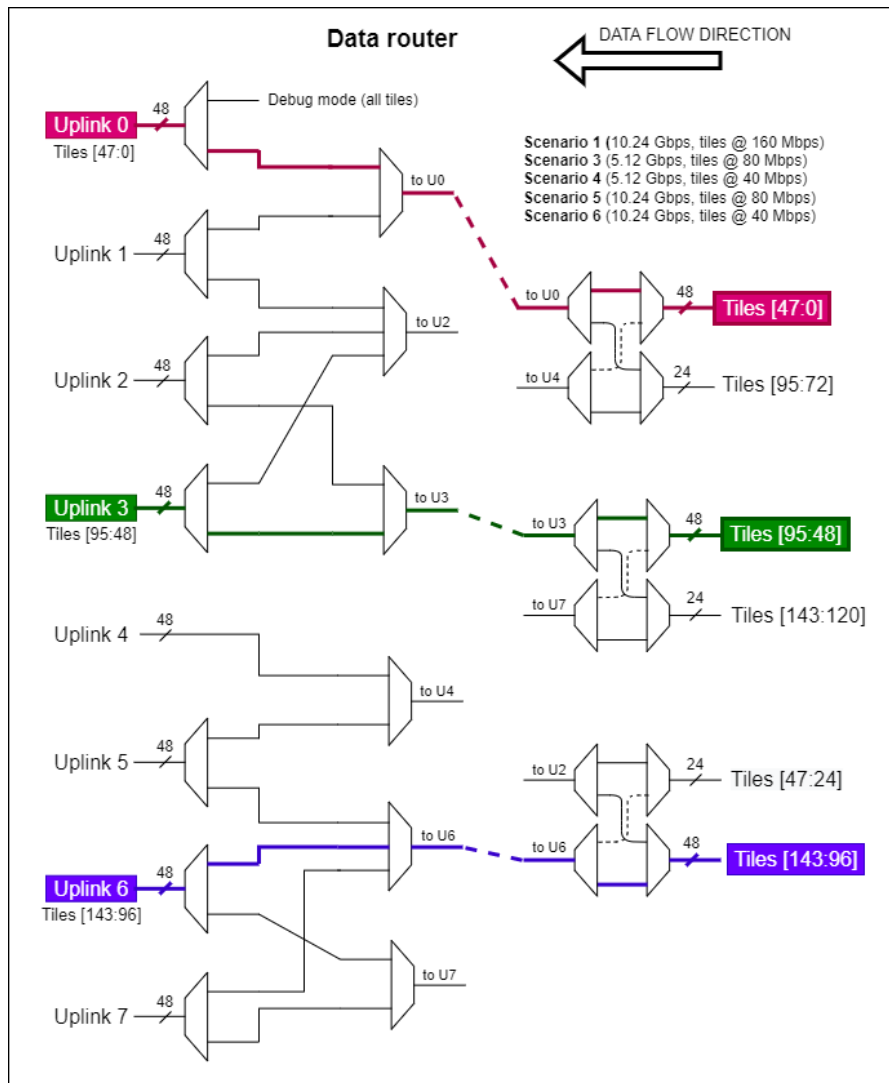
The data encoding block is the **IpGBT's TX** core
 160 Mbps x 144 = 22.5 Gbps
 Full capacity: 8 HS serializers = 80 Gbps (10 Gbps each, only 3 used)
 Fallback: 40 Gbps, 5 Gbps each (6 used)
 4 serializer data outputs drive one VTRx+

SVT Outer Barrel & Disks

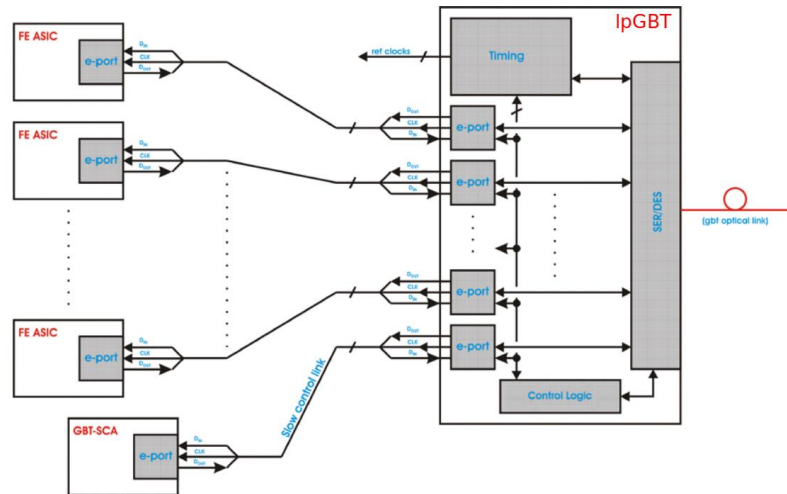
6-RSU LAS
 72 Tiles
 1 HS serializer = 10 Gbps

5-RSU LAS
 60 Tiles
 1 HS serializer = 10 Gbps

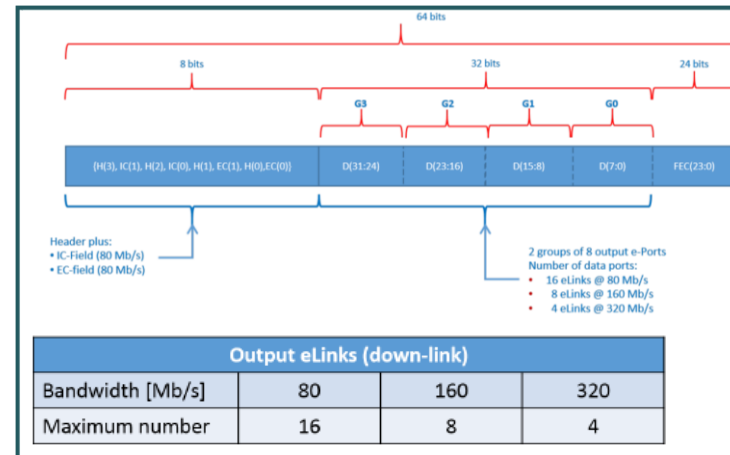
LEC Data Routing



IpGBT Protocol



- Front Ends connect to “e-links”
- The fiber protocol includes “Forward Error Correction”
- Downlink runs at 2.56 Gbps
 - Downlink frame is 64bit wide, of which 32 bits are payload
 - 1.28 Gbps payload
 - Up to 16 e-links @ 80 Mbps
- Uplink runs at either 10.24 Gbps or 5.12 Gbps
 - Uplink frame is either 128bit or 256bit
 - 256bit frame contains 192bits of payload (7.68 Gbps)
 - Up to 24 e-links at either 160 Mbps or 320 Gbps



Downlink
 Line Rate: **2.56 Gbps**
 32 out of 64 bits are data:
 Payload = **1.280 Gbps**

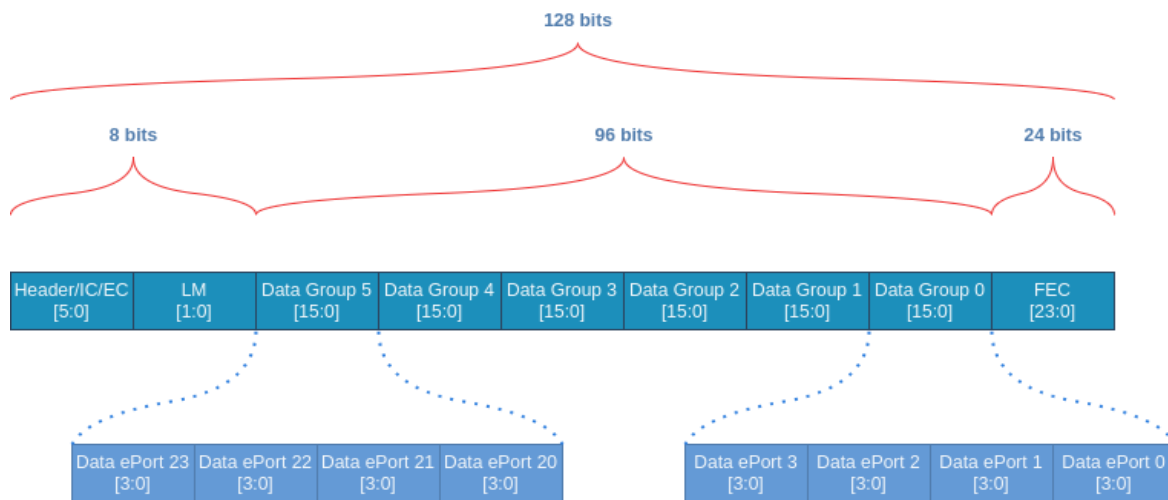
Data Uplink
 192 out of 256 bits are data:
 Payload = **7.680 Gbps**

Input eLinks (up-link)												
Up-link bandwidth [Gb/s]	5.12						10.24					
FEC coding	FEC5			FEC12			FEC5			FEC12		
Bandwidth [Mb/s]	160	320	640	160	320	640	320	640	1280	320	640	1280
Maximum number	28	14	7	24	12	6	28	14	7	24	12	6

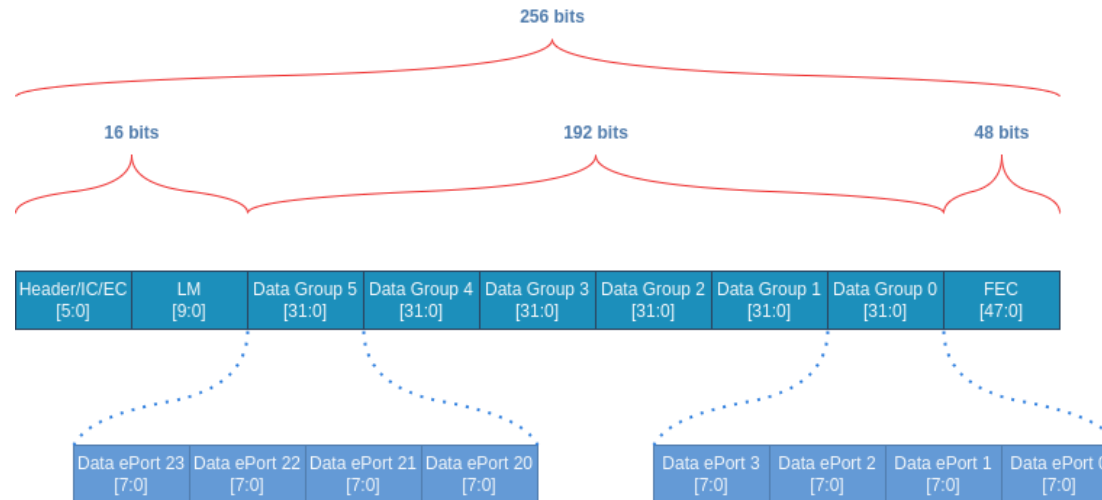
Field	5.12 Gbps		10.24 Gbps	
	FEC5	FEC12	FEC5	FEC12
Frame [bits]		128		256
Header [bits]		2		2
IC [bits]		2		2
EC [bits]		2		2
D [bits]	112	96	224	192
FEC [bits]	10	24	20	48
LM [bits]	0	2	6	10
Correction [bits]	5	12	10	24
# of eLink groups	7	6	7	6

IpGBT ePort Routing

5.12Gbps



10.24Gbps

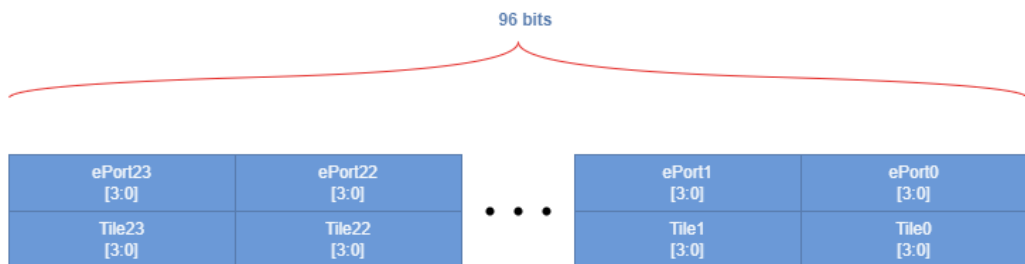


MOSAIX uplink						
Uplink bandwidth (Gbps)	5.12			10.24		
FEC Coding	FEC12			FEC12		
Tile bandwidth (Mbps)	40	80	160	40	80	160
Tiles per uplink ¹	48	48	24	48	48	48
Bits per tile	1	2	4	1	2	4
Tiles per ePort	2	2	1	2	2	2
Bits per ePort	4	4	4	8	8	8
Used bits per ePort	2	4	4	2	4	8
Bandwidth efficiency	50%	100%	100%	25%	50%	100%

1. To simplify routing scheme, 48 tiles are connected in instances where there are bandwidth enough to support a higher number of tiles.

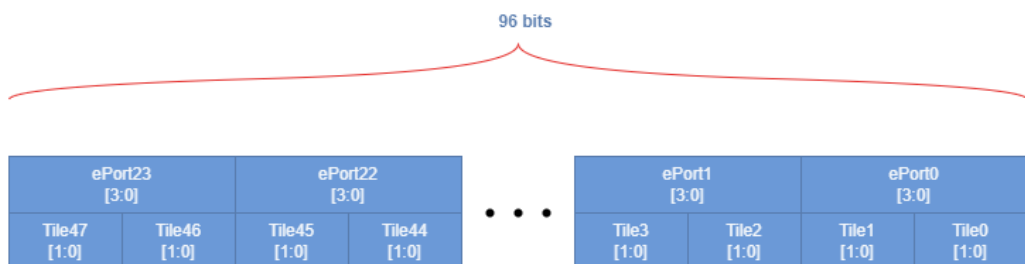
LEC Data Routing

5 Gbps / 160 MHz



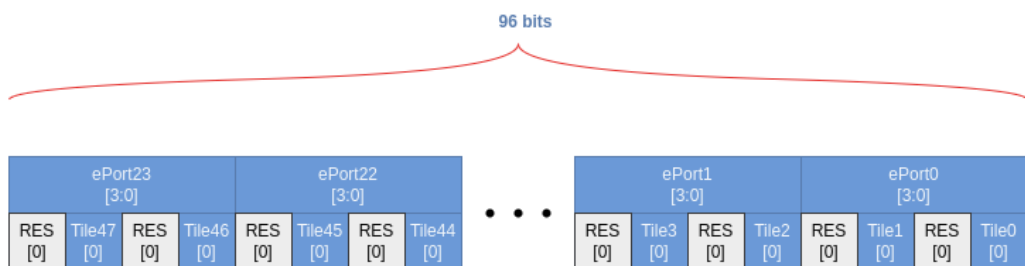
5 Gbps / 80 MHz

4 frames to reconstruct file word



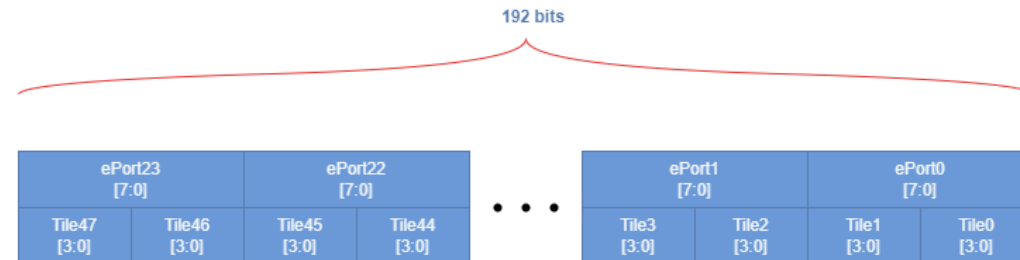
5 Gbps / 40 MHz

8 frames to reconstruct file word



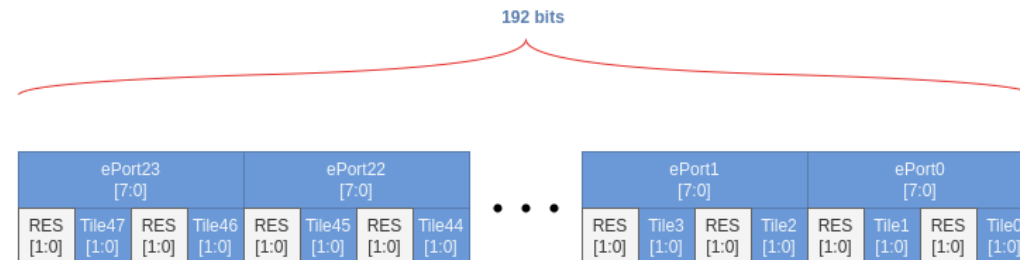
16 frames to reconstruct file word

10 Gbps / 160 MHz



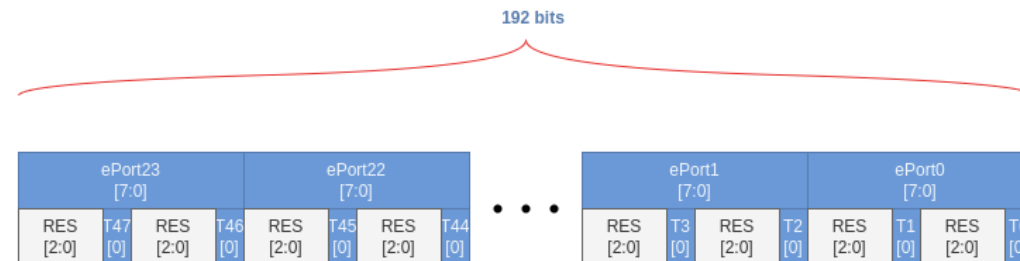
10 Gbps / 80 MHz

4 frames to reconstruct file word



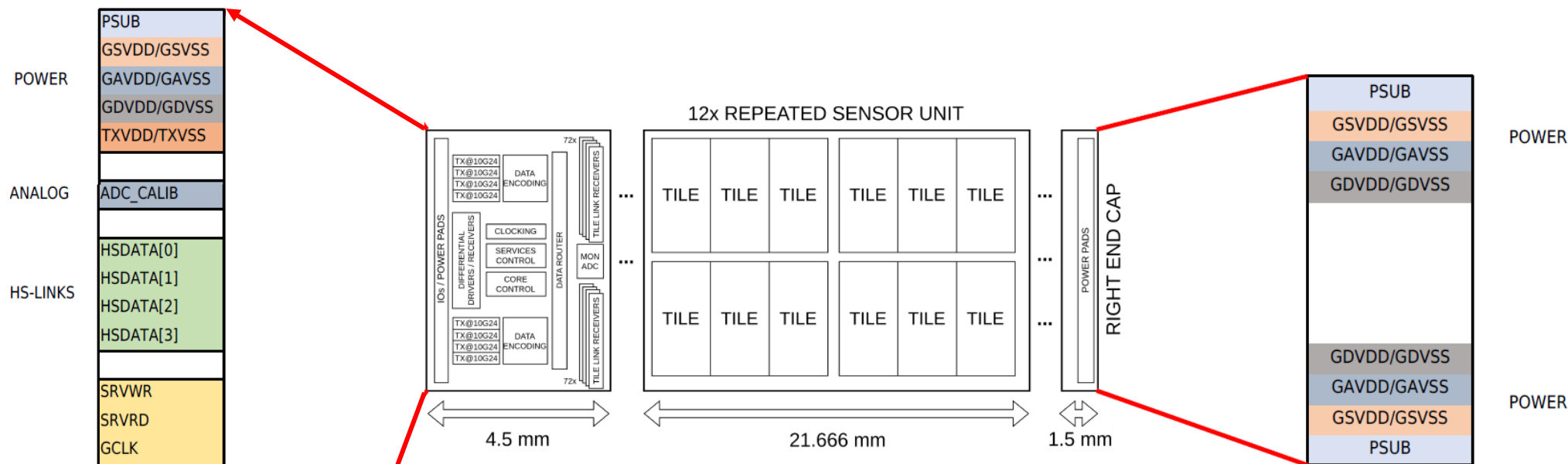
10 Gbps / 40 MHz

8 frames to reconstruct file word



16 frames to reconstruct file word

Supplies and I/Os



All I/Os are differential

8x 10.24 Gb/s data outputs

1x clock at 160 MHz

2x slow control buses at 5 Mbps

2x synchronization signals

(slow controls via IpGBT: 1 clk, 4 elink down, 2 elink up, 1 spare down)

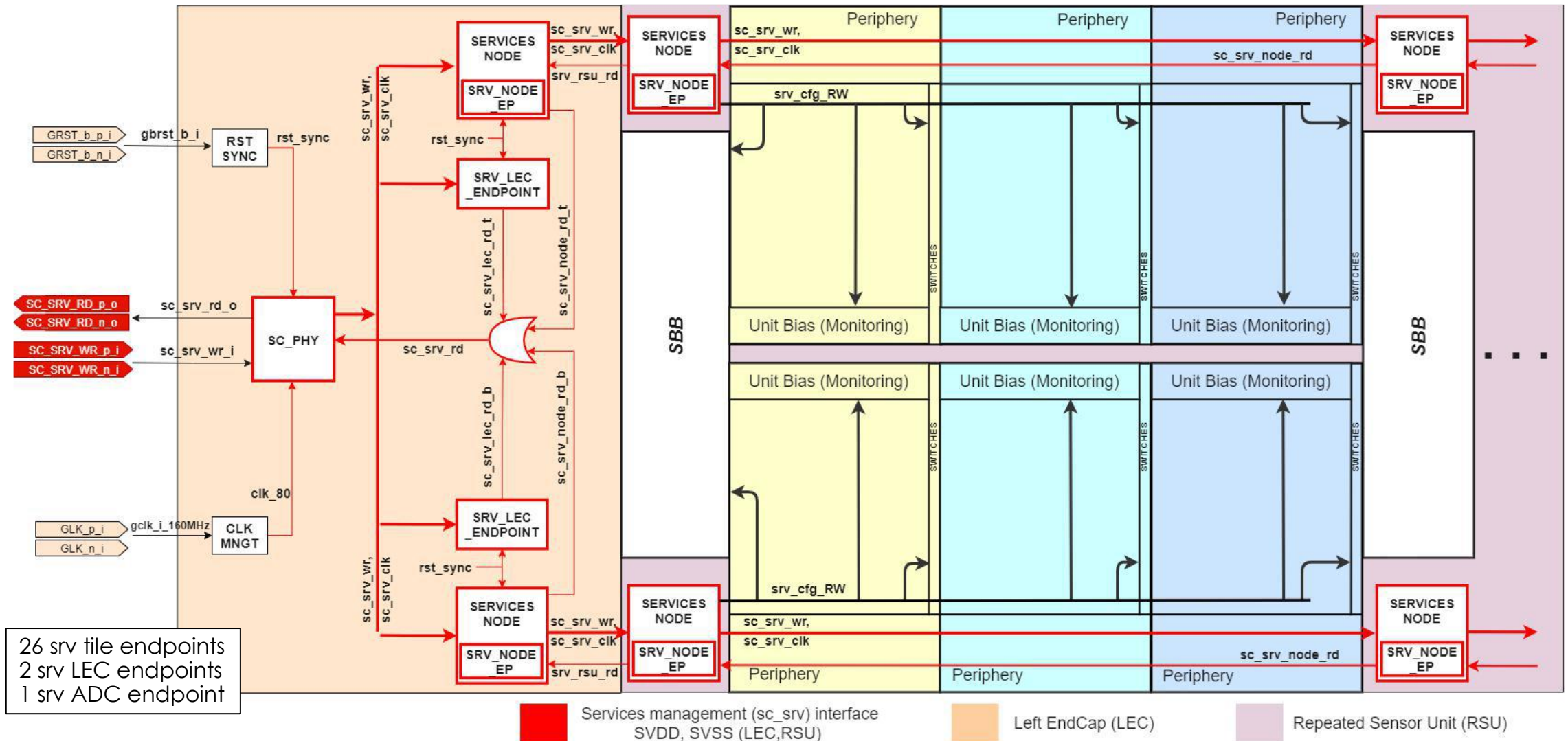
Global analog and digital supplies per segment

On-chip supply segmentation and control

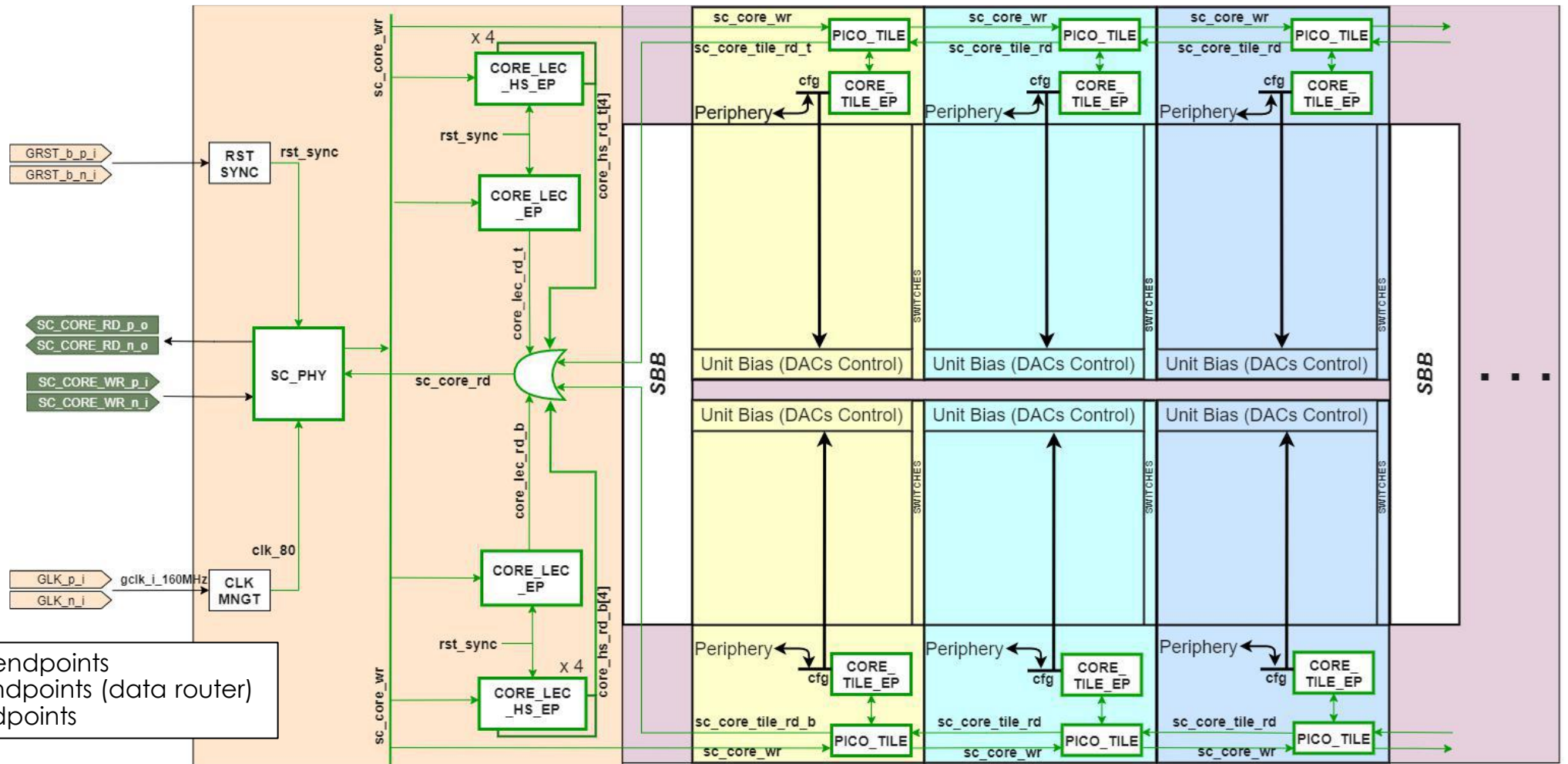
Reverse biasing of substrate (PSUB)

SVT LAS has power only from the LEC, no REC on LAS

Slow Controls Architecture: Services Control



Slow Controls Architecture: Chip Control



144 core tile endpoints
 2 core LEC endpoints (data router)
 8 core HS endpoints

Core management interface
 Left EndCap (LEC)
 Repeated Sensor Unit (RSU)

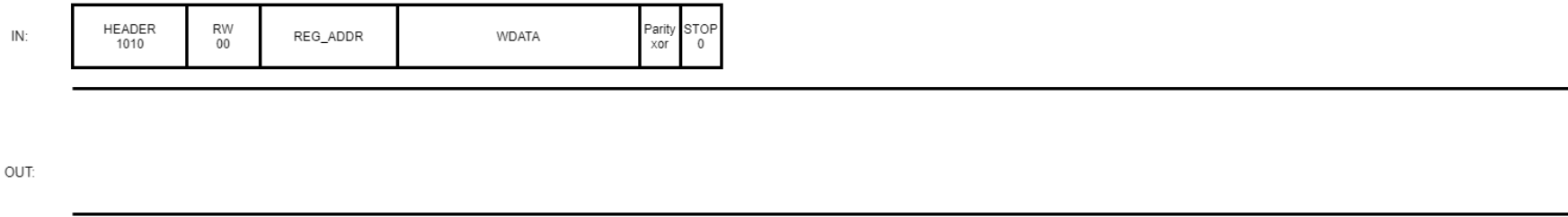
Slow Control Protocol

Field ID	Field Name	Width	Description
A	HDR	4	Fixed 4bit (4'hA) value that indicates a start of transaction
B	RW	2	Two bit field to indicate transaction type. 0: WRITE_posted transaction, 1: WRITE_non-posted transaction 2: READ transaction
C	EP_ADDR	8	Endpoint address
D	REG_ADDR	8	Register address
E	REG_DATA	16	Register write or read data
F	PARITY	1	Transaction parity bit (bit-wise xor of RW, EP_ADDR, REG_ADDR and REG_DATA fields)
G	STOP	1	Stop bit: 1'b0: Fixed 1bit (1'b0) value that indicates end of transaction

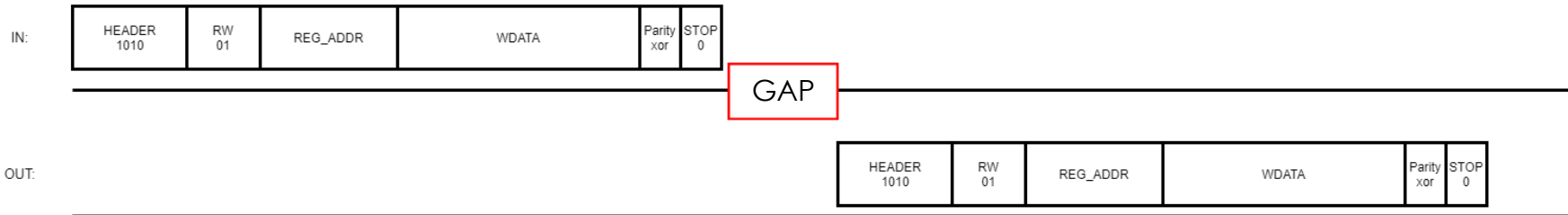
Transaction type	Direction	HDR	RW	ADDR	DATA	PARITY	STOP
WRITE_posted	Input to the ASIC	4'b1010	2'b00	Any valid register address	Data to write to the register	<i>xor</i> (HDR, RW, ADDR, DATA)	1'b0
WRITE_non-posted	Input to the ASIC	4'b1010	2'b01	Any valid register address	Data to write to the register	<i>xor</i> (HDR, RW, ADDR, DATA)	1'b0
WRITE-response	Output of the ASIC	4'b1010	2'b01	Register address as specified in the corresponding WRITE_non-posted transaction	Value of the register	<i>xor</i> (HDR, RW, ADDR, DATA)	1'b0
READ	Input to the ASIC	4'b1010	2'b10	Any valid register address	16'd0 (or 8'd0)	<i>xor</i> (HDR, RW, ADDR, DATA)	1'b0
READ-response	Output of the ASIC	4'b1010	2'b10	Register address as specified in the corresponding READ transaction	Value of the register	<i>xor</i> (HDR, RW, ADDR, DATA)	1'b0

Slow Control Transactions

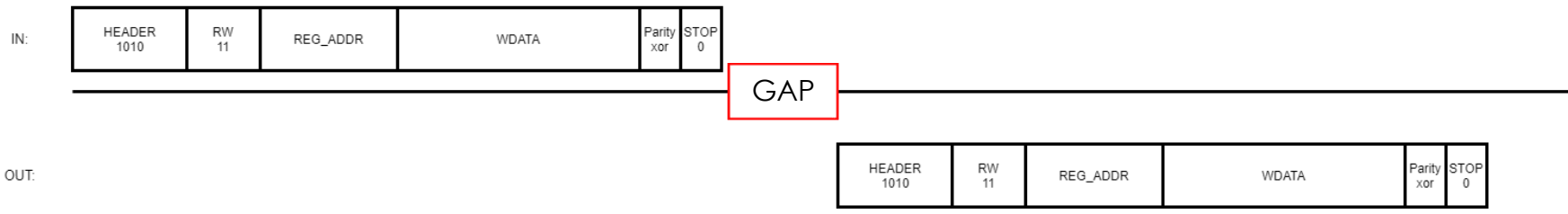
Posted Write Operation



Non-Posted Write Operation



Read Operation



How long does it take to run calibration scans?

- Duration largely depend on parallelism
- In final readout system, full parallel scans possible
- Sequential scans probably required for wafer testing

	Powering (s)	Matrix configuration (s)	Integration (s)	Readout chip (s)	Readout backend (s)	Total
Parallel	0.5	121	568	92	538	20 minutes
Sequential	72	9212	81838	13258	538	29 hours

Assumptions:

- Threshold scan
- DAC resolution: 256
- Pulses per settings: 50
- Integration window: 100 us
- Gap between rows: 1000 us
- Readout polling: 500 us

Main contributors



How long does it take to configure the pixel matrix?

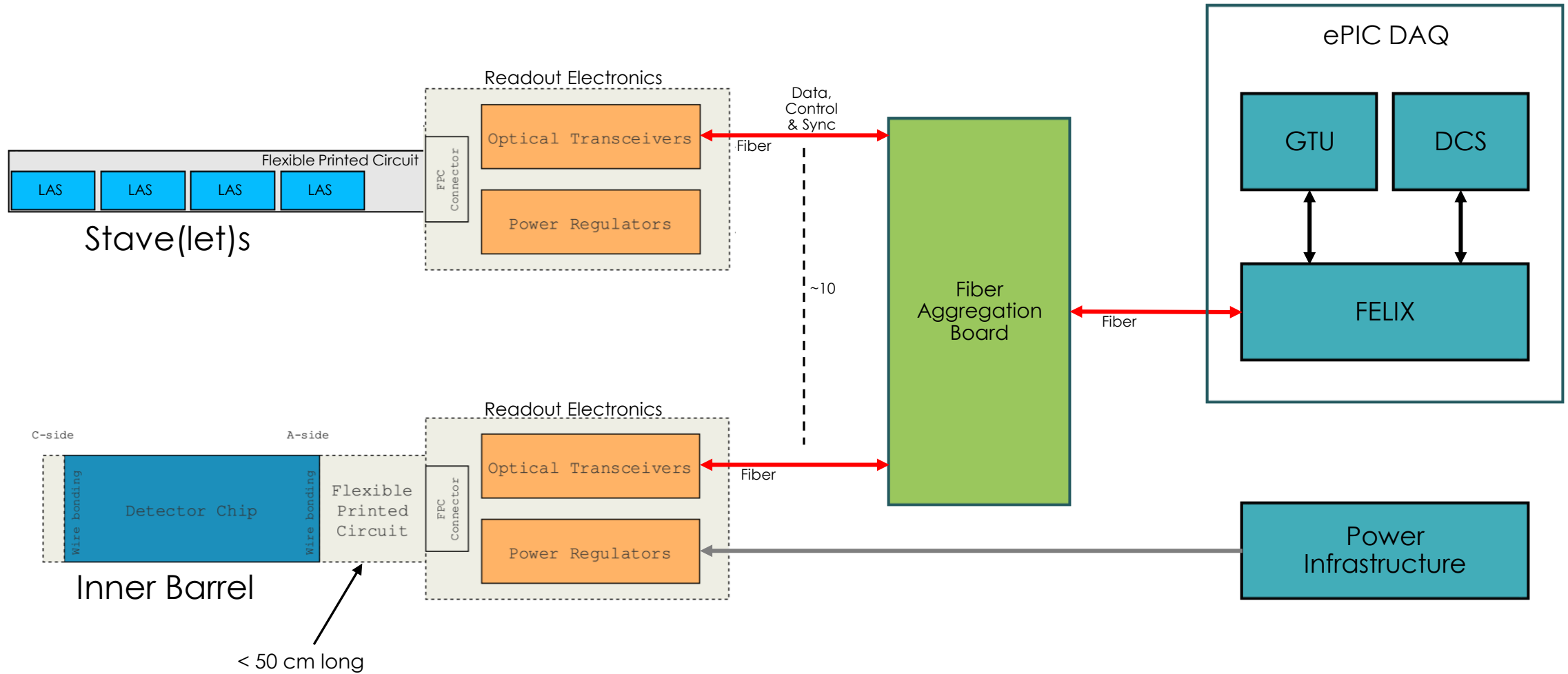
- Pixels configuration via periphery slow control endpoint
- Configuration accomplished by 4 actions:
 - Set configuration value
 - Select rows
 - Select columns
 - Commit

- Assuming the need to mask 1% of pixels:
- **Time to configure 1 tile: 0.028 seconds**
- **Time to configure a segment: 4 seconds**

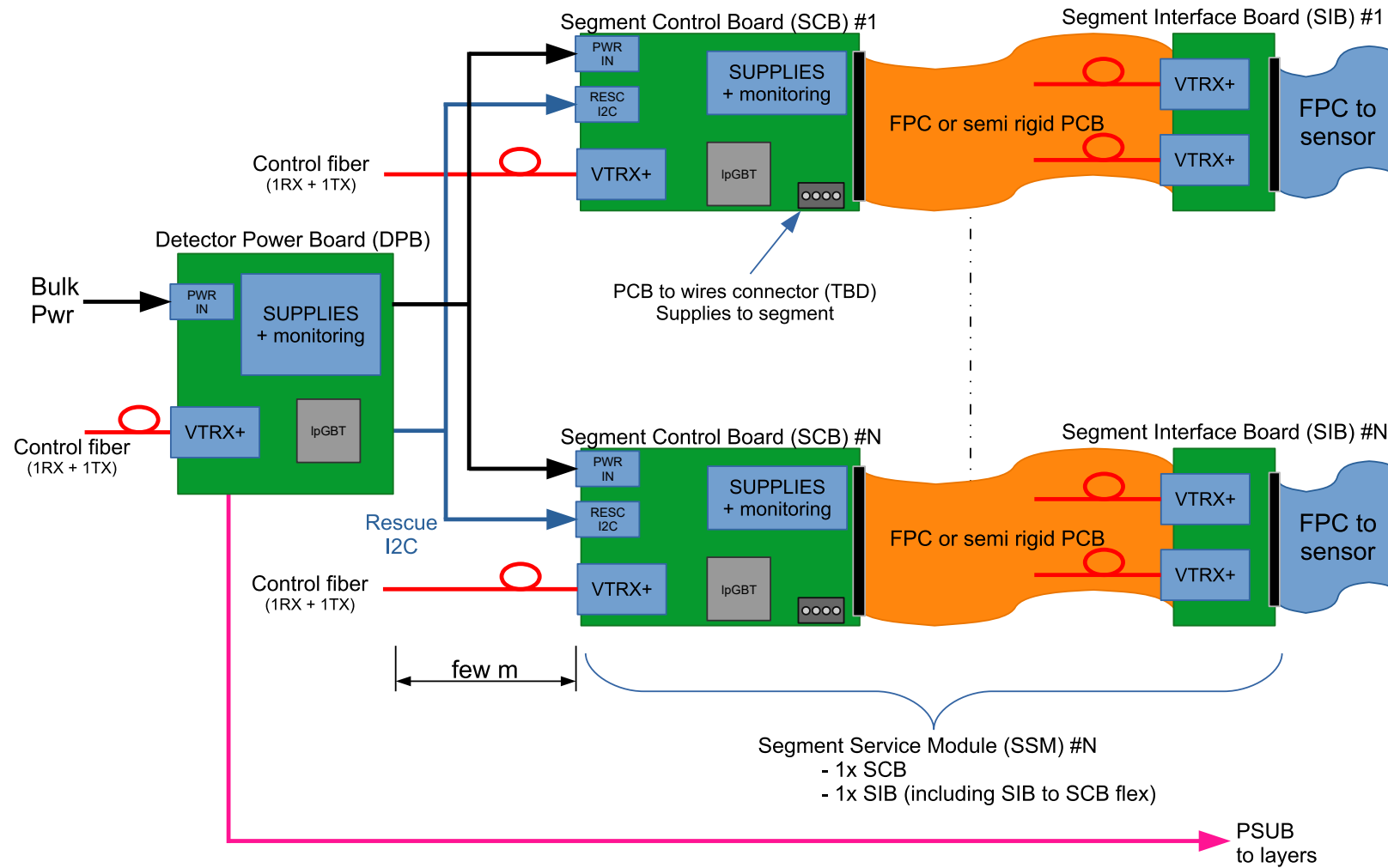
Configuration Scrubbing & Monitoring

- To ensure that all pixels keep their configuration during a run, the configuration should be updated with regular intervals.
- For scrubbing, individual pixels must be addresses, to avoid overwriting any non-default configuration
- Time to execute scrub cycle 1 tile: 2.8 seconds
- **Time to execute scrub cycle segment: 7 minutes**
- Tile readout monitoring:
 - Assuming less than 50 registers to monitor per tile
 - **< 200 ms** per segment

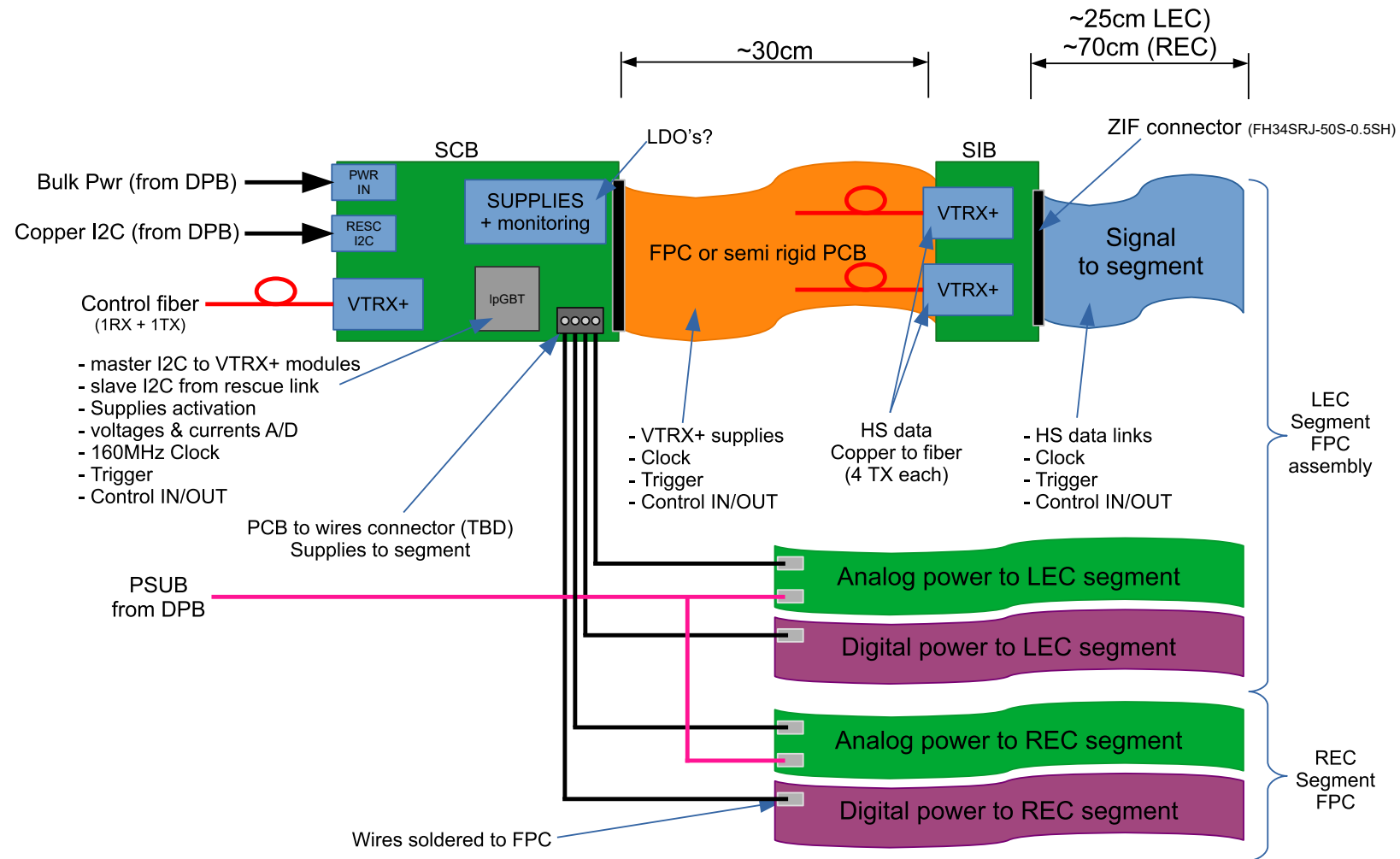
SVT Electronics – Simplified Overview



IB Readout Architecture

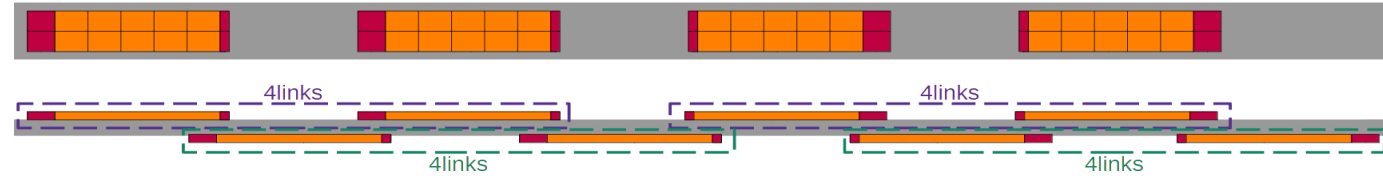
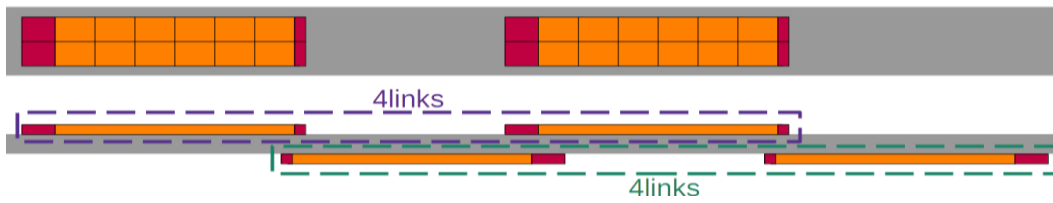


Readout Segment Architecture



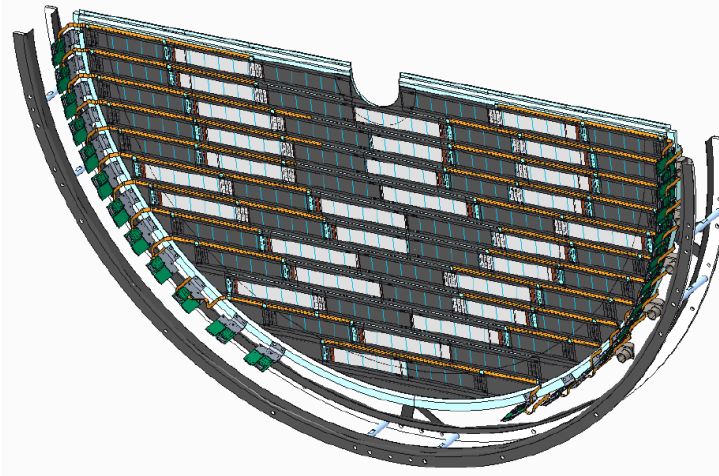
Disk/Outer Barrel Readout Configuration

Outer Barrel Layer 3

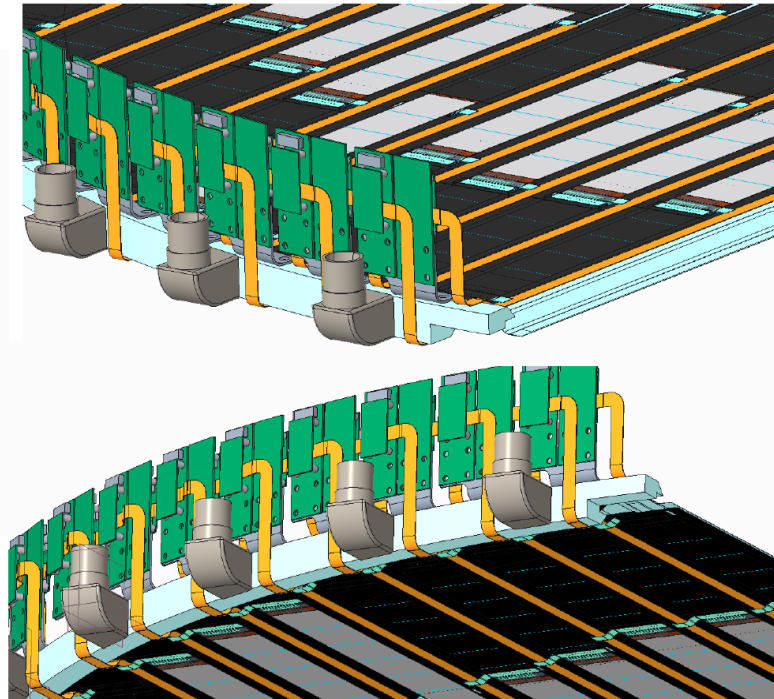


Outer Barrel Layer 4

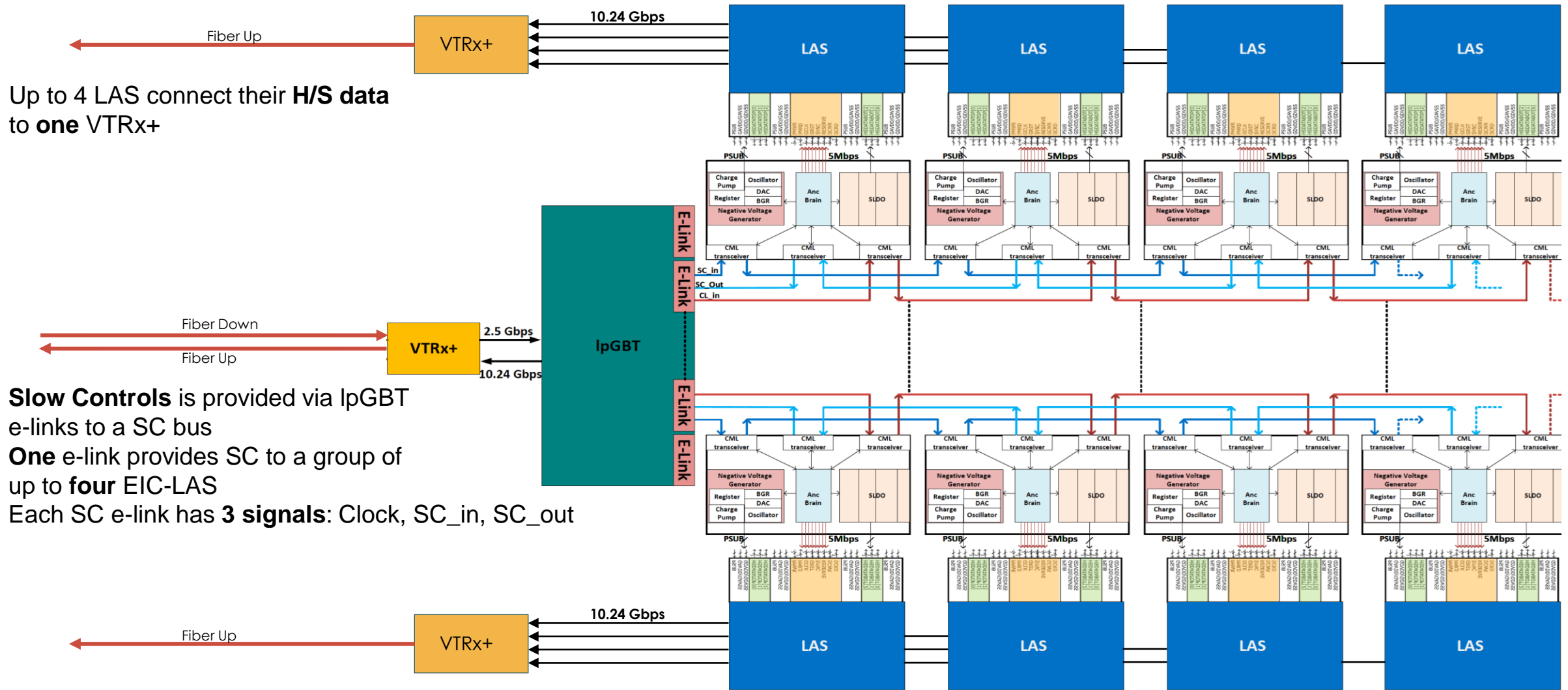
Readout boards



Disks



Outer Barrel and Disk Readout Electronics



Up to 4 LAS connect their **H/S data** to **one VTRx+**

Slow Controls is provided via IpGBT e-links to a SC bus

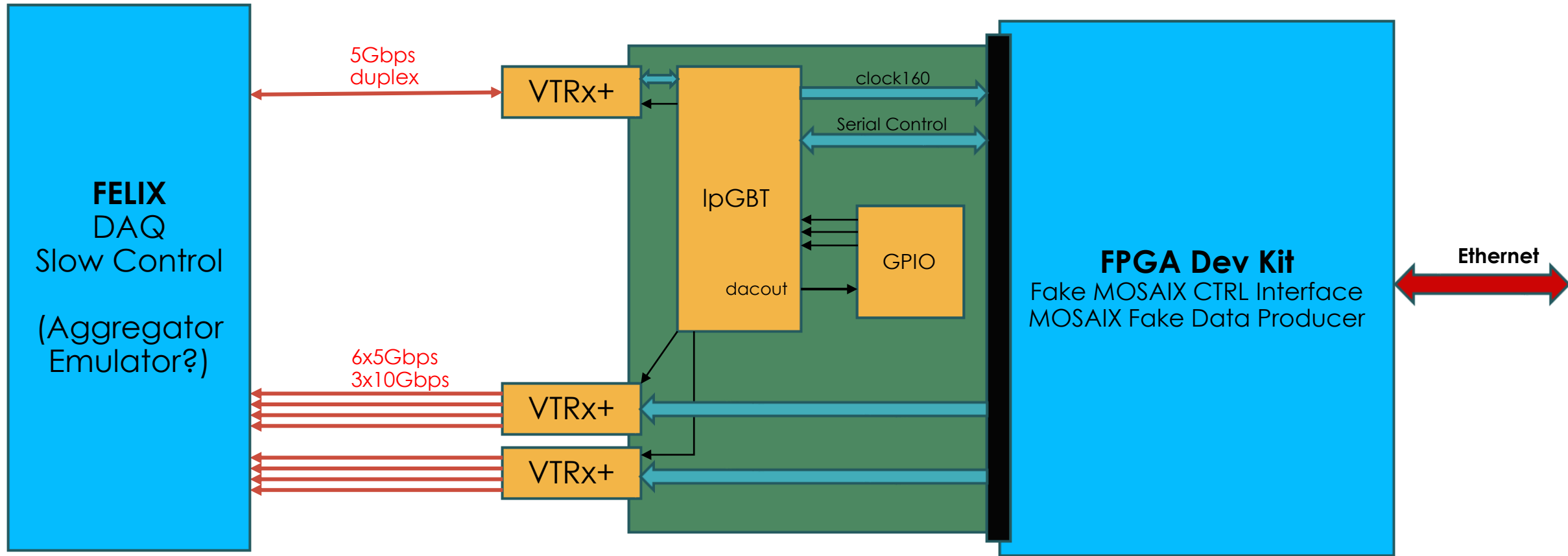
One e-link provides SC to a group of up to **four** EIC-LAS

Each SC e-link has **3 signals**: Clock, SC_in, SC_out

Assumptions for SVT IpGBT & VTRx+ Needs

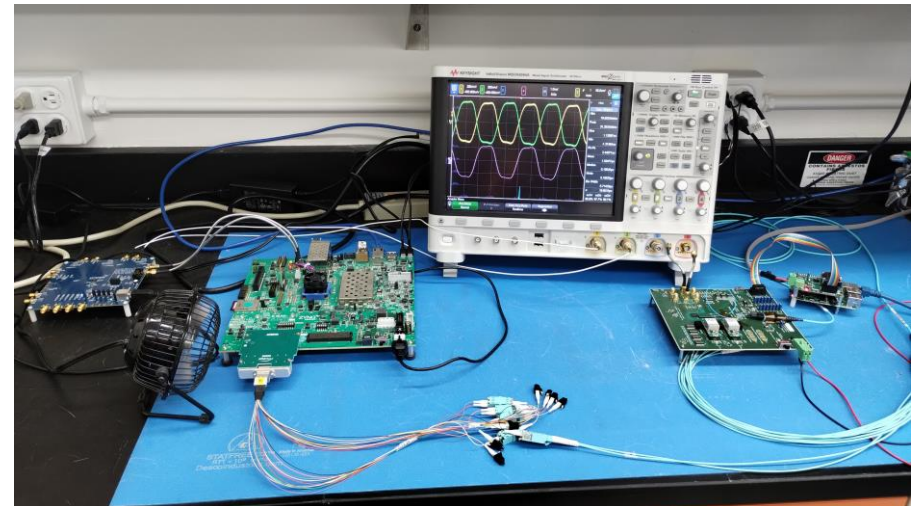
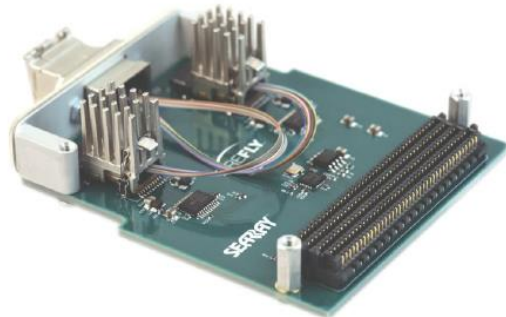
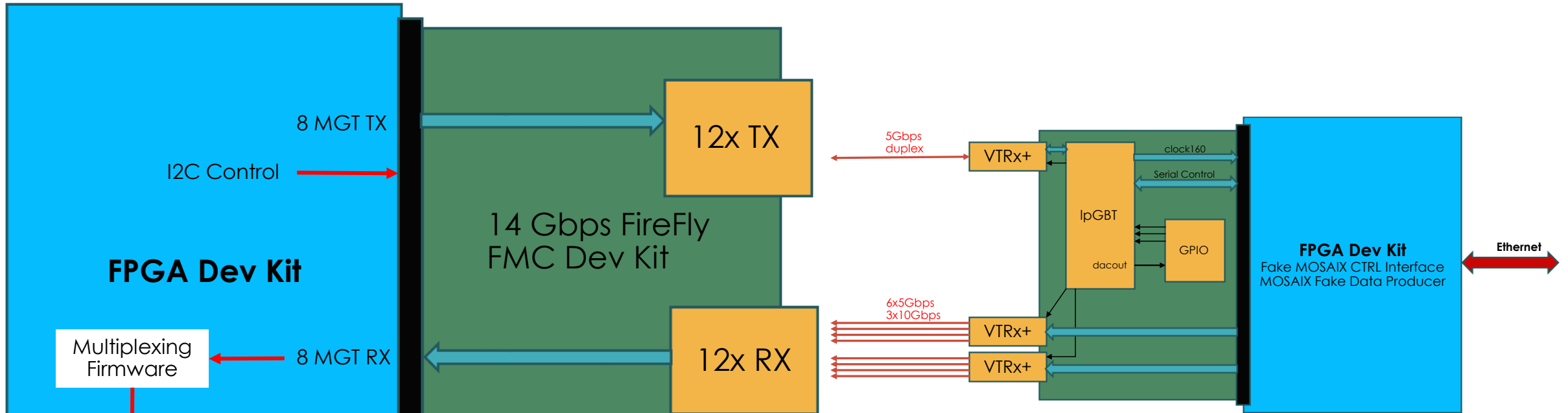
- Each VTRx+ has 4 TX and 1 RX fiber
- Each IpGBT provides **16** output elinks on downlink side
 - Up to **4** of those are used for RDO internal use
 - Up to **12 down elinks** are available for slow controls
 - Uplink count needs are equal or smaller than downlink count needs
- For data up to 4 Readout links are connected to 1 VTRx+ where geometrically possible
- For slow controls on the **IB**, each of the 5 downlink control lines are connected individually to IpGBT output elinks
 - Each IpGBT is assumed to be used to serve (up to) **2 Segments**
- For slow controls on the **OB** and **Disks**, each “Module” (up to 4 LAS) is multiplexed to 1 elink (up and down)
 - Each IpGBT is assumed to be used to serve (up to) **8 “Modules”**
- Each IpGBT requires 1 VTRx+ (1 TX & 1 RX used)

MOSAIX Hardware Mockup



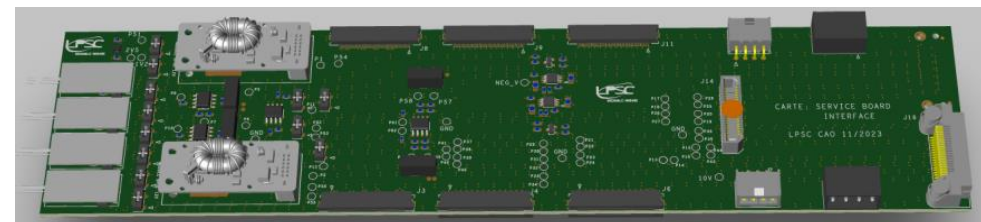
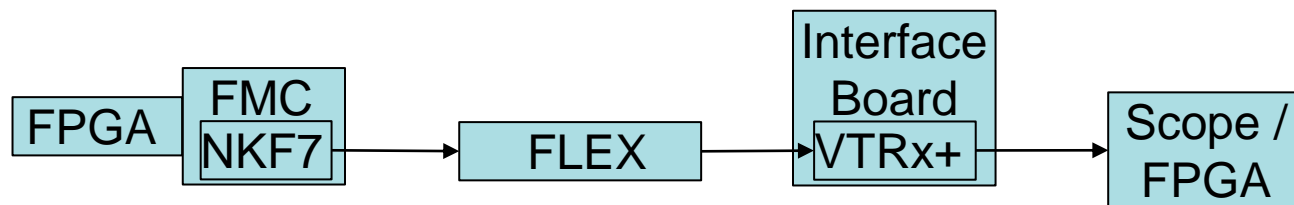
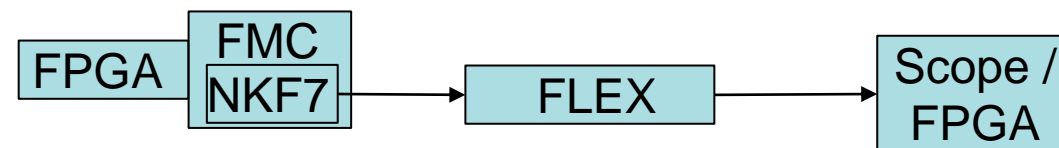
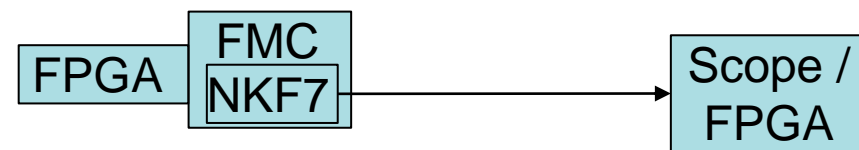
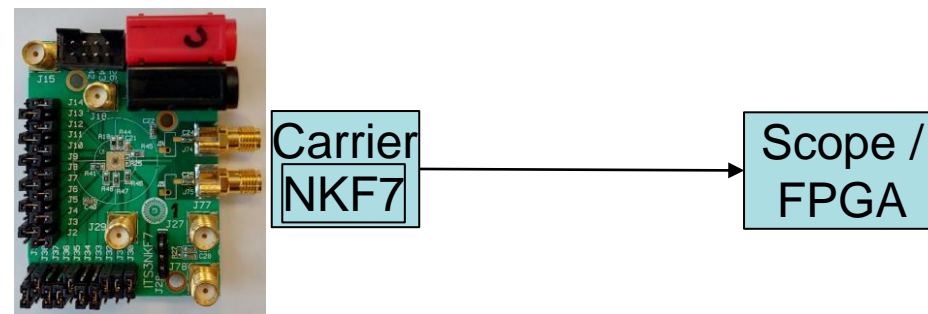
VTRx+ connected to FMC HPC (8 MGT available), emulate typical packets

Aggregator Board Prototyping



NKF7 Serializer Test Steps

- Characterize NKF7 with fixed 16-bit pattern
 - Scope eye-pattern
 - FPGA BER test
 - Radiation test with Prague 32 MeV protons
- Characterize NKF7 with variable pattern
- Characterize NKF7 + Flex (design by Antoine)
 - Scope eye-pattern
 - FPGA BER test & statistical eye
- Characterize NKF7 + Flex + VTRx+ Transceiver
 - Scope eye-pattern (optical probe or after minipods on CRU)
 - Receiver (minipod / FPGA / CRU) BER test

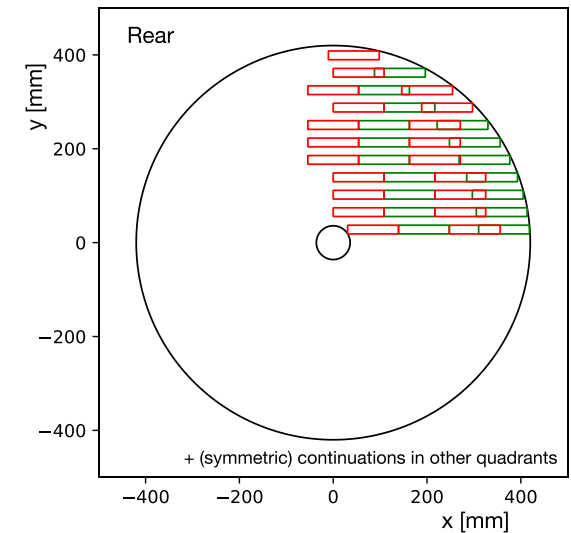
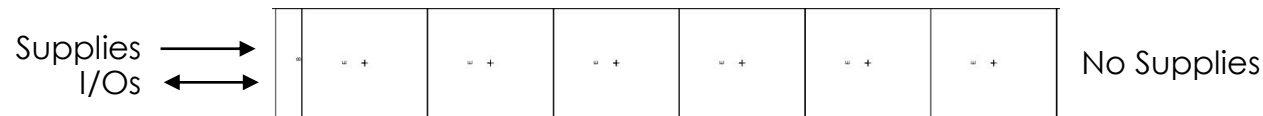
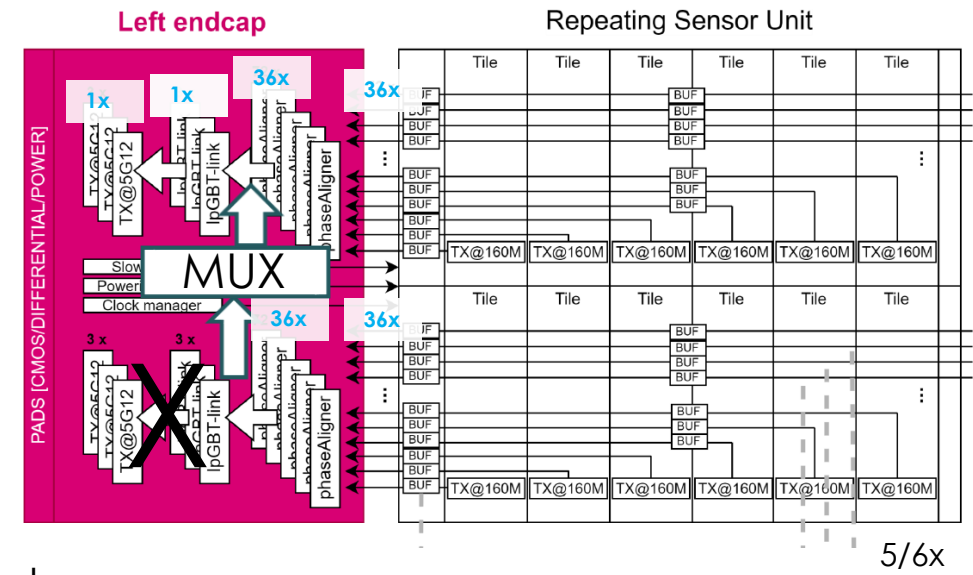


Backup

ePIC SVT: “Large Area Sensor” (LAS)

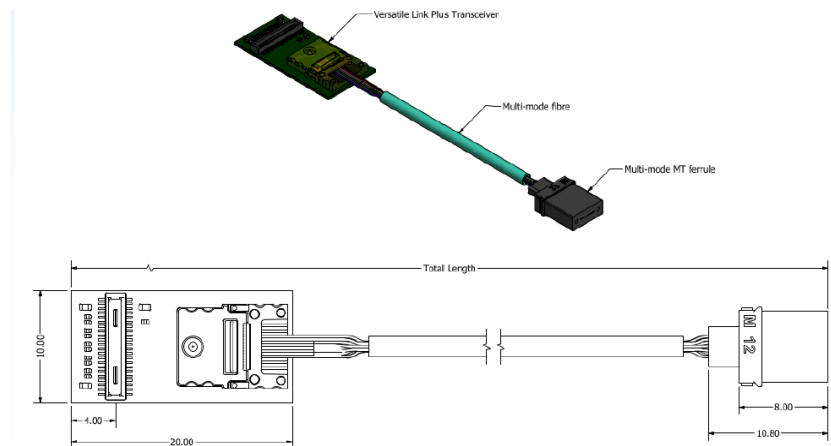
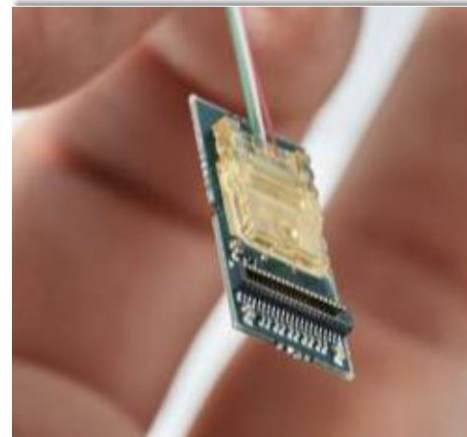
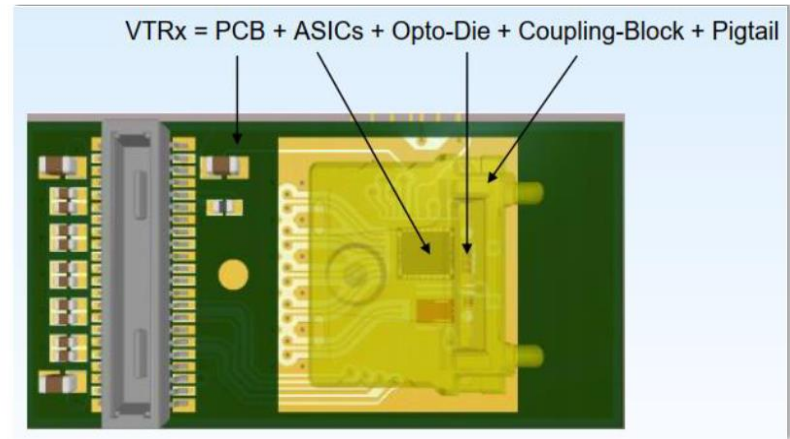
- **Inner Barrel** (Layers 0,1,2) will reuse ITS3-like sensors as is
 - **Layer 0:** 4 sensors in r-phi, 3 segments of 12 RSU
 - **Layer 1:** 4 sensors in r-phi, 4 segments of 12 RSU
 - **Layer 2:** 8 sensors in r-phi, 5 segments of 12 RSU
- EIC **variant** for the **Outer Barrel** (Layers 3,4) and **Endcap Disks**
 - “Large Area Sensor” (LAS)
 - Will be stitched, but not to wafer scale
 - Likely 1 Segment of 5 or 6 RSU (no need for right endcap)
 - The intention is to multiplex Tile data lines to 1 High-Speed output
 - More conventional carbon composite mechanical support with integrated cooling

6-RSU LAS



VTRx+ Front-end Module

- **Versatile**
 - Up to 4 Tx + 1 Rx, configurable by masking channels
- **Miniaturised**
 - 20 x 10 x 2.5 mm
- **Pluggable**
 - Electrical connector
- **Data-rate**
 - Tx: up to 4x10 Gb/s, Rx: 2.5 Gb/s
- **Environment**
 - Temperature: -35 to + 60 °C
 - Total Dose: 100 Mrad
 - Total Fluence: 1×10^{15} n/cm² and 1×10^{15} hadrons/cm²
- **Status**
 - Pre-production ongoing
 - Solving problems with module assembly
 - Alignment of optical components
 - Ramping up to 2k modules/month in 2023



Remark on timing

Projections for timing resolution

Targeting figures similar to ALPIDE

Continuous mode readout

Integration period: 5 / 10 / 20 μs

Frame rate: 200 / 100 / 50 kHz

Low power constrains response speed

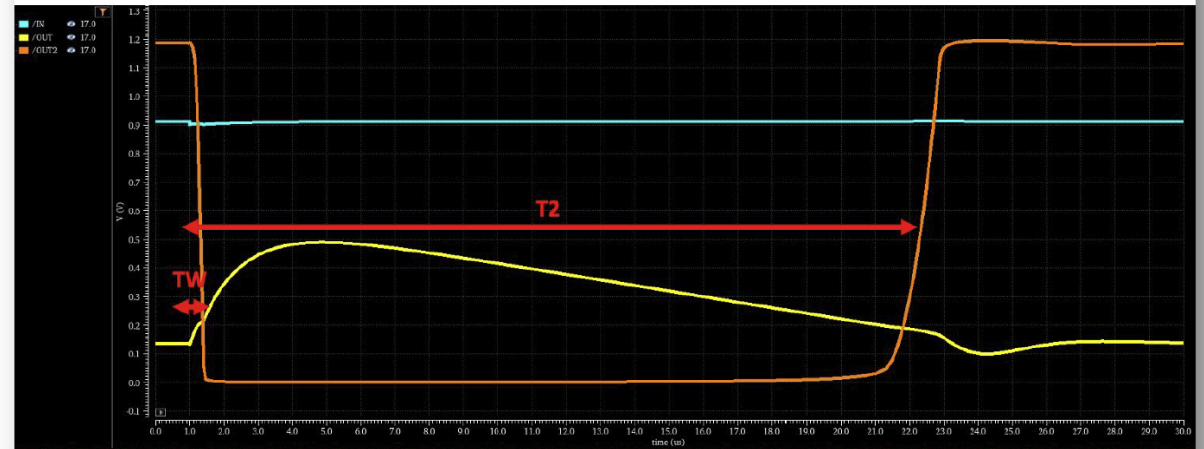
MOSS pulse duration 40 μs @ 1 ke

MOSS time walk $\sim 3.3 \mu\text{s}$

Reviewing timing specs for next design

Discriminator time window

(MOSS, nominal bias for low power)



Discriminator time window

